



Material Content Data Sheet



Sales Product Name				IPB039N10N3 G		Issued		20. July 2018	
MA#				MA001263090					
Package				PG-TO263-7-3		Weight*		1526.77 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	8.861	0.58	0.58	5804	5804	
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		526		
	inorganic material	phosphorus	7723-14-0	0.241	0.02		158		
	non noble metal	copper	7440-50-8	801.714	52.50	52.57	525103	525787	
wire	non noble metal	aluminium	7429-90-5	11.518	0.75	0.75	7544	7544	
encapsulation	organic material	carbon black	1333-86-4	8.679	0.57		5685		
	plastics	epoxy resin	-	95.471	6.25		62531		
	inorganic material	silicondioxide	60676-86-0	474.463	31.08	37.90	310761	378977	
leadfinish	non noble metal	tin	7440-31-5	12.317	0.81	0.81	8067	8067	
plating	non noble metal	nickel	7440-02-0	0.269	0.02		176		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	525102	176	
solder	noble metal	silver	7440-22-4	0.152	0.01		100		
	non noble metal	tin	7440-31-5	0.122	0.01		80		
	non noble metal	lead	7439-92-1	5.815	0.38	0.40	3809	3989	
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		70		
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21		
	non noble metal	copper	7440-50-8	106.210	6.96	6.97	69565	69656	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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